



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON) MAX}	Package	I _D T _A = +25°C
30V	$40m\Omega @ V_{GS} = 10V$	SC59	5.1A
30 V	$50m\Omega$ @ $V_{GS} = 4.5V$	3039	4.3A

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

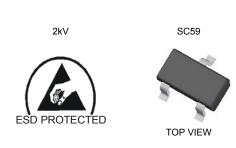
- Load Switch
- DC-DC Converters
- Power Management Functions

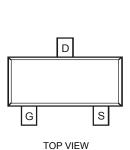
Features

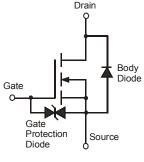
- Low On-Resistance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SC59
- Case Material Molded Plastic. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Solderable per MIL-STD-202, Method 208 (e3)
- Terminal Connections: See Diagram
- Weight: 0.014 grams (approximate)
- •







Pin Configuration Equivalent Circuit

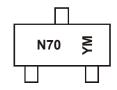
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3070SSN-7	SC59	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html

Marking Information



N70 = Product Type Marking Code YM = Date Code Marking Y = Year ex: Z = 2012 M = Month ex: 9 = September

Date Code Key

Year	2010	2011	2012	2013	2014	2015	2016	2017
Code	X	Y	Z	Α	В	С	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note C) / 40\/	Steady State	T _A = +25°C T _A = +70°C	I _D	4.2 3.3	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t<10s	T _A = +25°C T _A = +70°C	I _D	5.1 4	А
Continuous Drain Current (Note C) \ 4 E\/	Steady State	T _A = +25°C T _A = +70°C	I _D	3.7 2.8	А
Continuous Drain Current (Note 6) V _{GS} = 4.5V	t<10s	T _A = +25°C T _A = +70°C	I _D	4.3 3.3	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	60	Α		
Maximum Body Diode Forward Current (Note 6)			I _S	2	Α

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	ם	0.78	w	
Total Power Dissipation (Note 5)	T _A = +70°C	P_{D}	0.5	vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state		160	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	115	°C/W	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	D	1.3	W	
Total Fower Dissipation (Note 0)	$T_A = +70^{\circ}C$	P_{D}	0.8	VV	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	Б	96	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	68	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	18	°C/W		
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C		

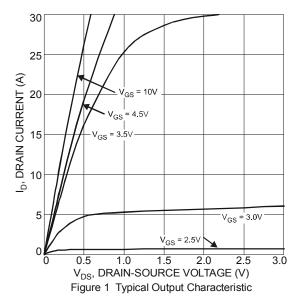
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

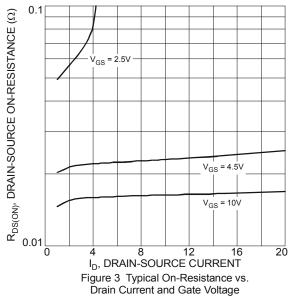
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	V _{DS} =24V, V _{GS} = 0V	
Gate-Body Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)	<u> </u>						
Gate Threshold Voltage	$V_{GS(th)}$	1.1	_	2.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Dunin Source On Desistance	-	_	24	40	0	$V_{GS} = 10V, I_D = 4.2A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	30	50	mΩ	$V_{GS} = 4.5V, I_D = 2A$	
Forward Transfer Admittance	IY _{fs} I	_	2.7	_	S	V _{DS} = 5V, I _D =4.2A	
Diode Forward Voltage	V _{SD}	_	0.75	1.0	V	V _{GS} = 0V, I _S = 1A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	697	_	pF	15)()(
Output Capacitance	Coss	_	97	_	pF	V _{DS} = 15V, V _{GS} = 0V - f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	67	_	pF	T = 1.0MHZ	
Gate Resistance	R_g	_	1.47	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	-	6	_			
Total Gate Charge (V _{GS} = 10V)	Q_g	-	13.2	_	nC	V _{DS} = 15V, I _D = 9A	
Gate-Source Charge	Q_gs	_	2.2	_	110	VDS - 15V, ID - 9A	
Gate-Drain Charge	Q_{gd}		1.8	_			
Turn-On Delay Time	$t_{D(ON)}$	_	4.3	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	_	4.4	_	ns	V_{DD} =15V, V_{GEN} =10V, R_{GEN} =6 Ω ,	
Turn-On Rise Time	t _r	_	20.1	_	ns	R _L =15Ω	
Turn-Off Fall Time	t _f		4.1	_	ns		
Reverse Recovery Time	t _{rr}	_	7.3	_	Ns	IF = 9A, di/dt = 500A/µs	
Reverse Recovery Charge	Qrr	_	7.9	_	nC	IF = 9A, di/dt = 500A/µs	

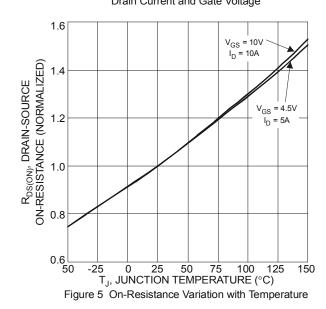
Notes:

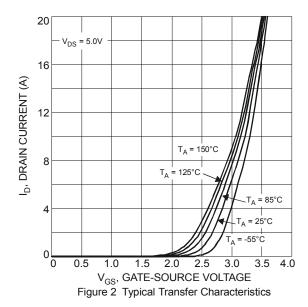
- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided. The power dissipation P_D is based on t<10s R_{BJA} .
- 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2 oz. Copper, single sided. The power dissipation P_D is based on t<10s R_{BJA} .
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

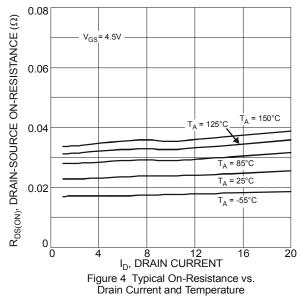


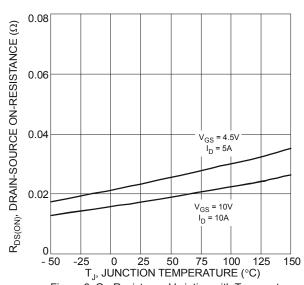














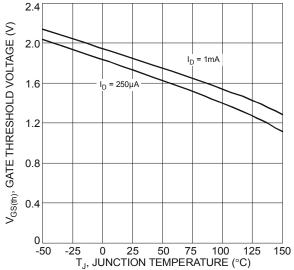


Figure 7 Gate Threshold Variation vs. Ambient Temperature

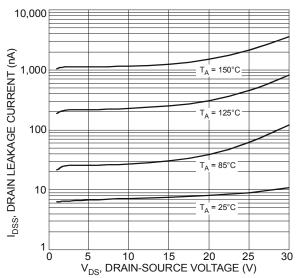
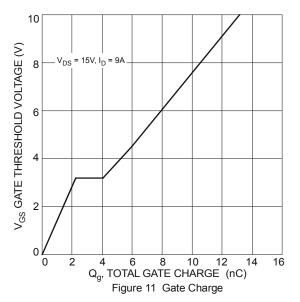
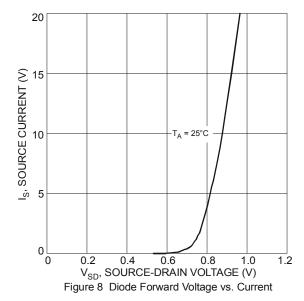
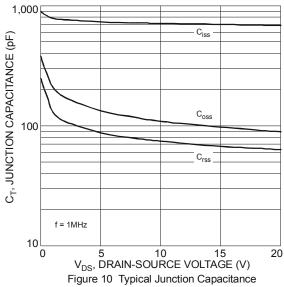


Figure 9 Typical Drain-Source Leakage Current vs. Voltage



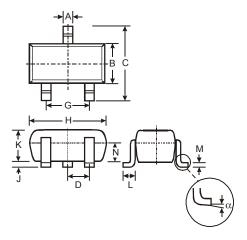






Package Outline Dimensions

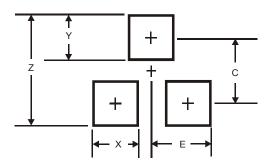
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SC59								
Dim	Min	Max	Тур						
Α	0.35	0.50	0.38						
В	1.50	1.70	1.60						
С	2.70	3.00	2.80						
D	-	-	0.95						
G	-	-	1.90						
Н	2.90	3.10	3.00						
J	0.013	0.10	0.05						
K	1.00	1.30	1.10						
L	0.35	0.55	0.40						
M	0.10	0.20	0.15						
N	0.70	0.80	0.75						
α	0°	8°	-						
All									

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.4
Х	0.8
Υ	1.0
С	2.4
F	1.35



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